Bid Notification for Solder Ball Bumper—info. will appear on an external-facing bid on Sandia’s site.

Contractor shall deliver Solder Ball Bumper SB2-SM or equivalent with the following additional components.

1. Automatic Laser Alignment
2. Integrated Laser Power Meter
3. Bond Head for Solder Balls < 60um
4. Bond Head for Solder Balls > 60 and < 150um
5. Bond Head for Solder Balls >150um
6. Pattern Recognition and Fiducial Alignment
7. Bond Head Laser Cleaning
8. 8” stage/working area